

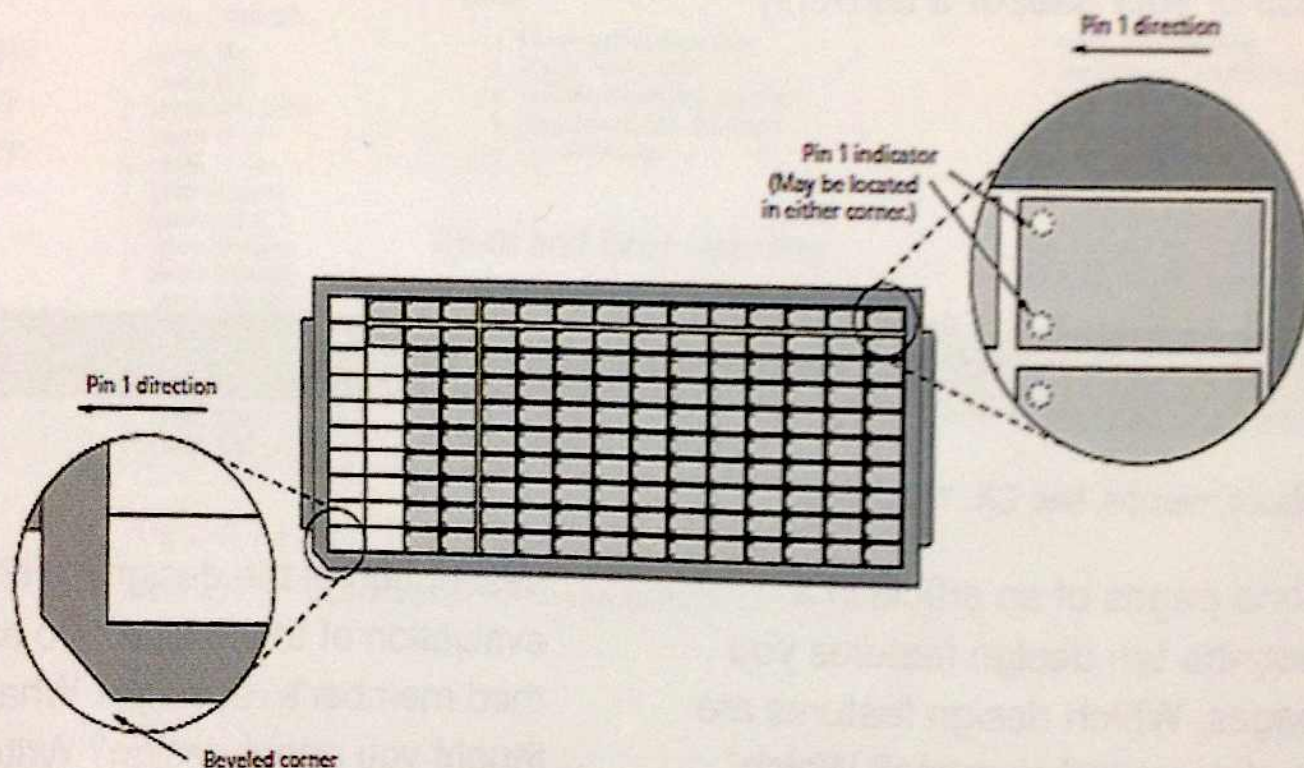
Pin 1 Orientation for Tray and Tape-and-Reel Packaging

Pin 1 refers to the location of the first lead or ball inside a semiconductor device and is used to determine how a part is attached to a circuit board. In a corner on the topside of each Micron device, pin 1 is indicated by an indentation, either a molded dot or a molded "MT," or it is indicated by a mark, specifically, a laser-etched dot or a laser-etched "MT." This section explains the locations of the pin 1 indicators on Micron's devices shipped in tray and tape-and-reel packaging.

Location of Pin 1 in Tray Packaging

Micron uses several different types of trays with varying colors for shipping products. However, each tray has a single beveled corner that indicates the direction pin 1 faces on each device. Depending on the package type and the design ID of the part, the pin 1 indicator will be located in one of the two corners of the device edge closest to the beveled corner of the tray. An example is shown in Figure 10.

Figure 10: Pin 1 Direction on Trays



Location of Pin 1 in Tape-and-Reel Packaging

Depending on their package type and design ID, devices shipped in tape-and-reel carriers are positioned so that the pin 1 indicator on each device is located in one of the two corners that faces the edge of the carrier tape with the round sprocket holes. Figure 11 on page 10 illustrates the position of the pin 1 indicators on Micron's tape-and-reel carriers.